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- The contents of this catalog are applicable to the products which are purchased from our sales offices or distributors (so called "TAIYO YUDEN's official sales channel").

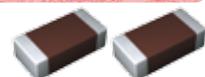
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MULTILAYER CERAMIC CAPACITORS



WAVE REFLOW

PARTS NUMBER

J	M	K	3	1	6	△	B	J	1	0	6	M	L	—	T	△
①	②	③	④	⑤	⑥	⑦	⑧	⑨	⑩	⑪	⑫					

△=Blank space

① Rated voltage

Code	Rated voltage[VDC]
P	2.5
A	4
J	6.3
L	10
E	16
T	25
G	35
U	50
H	100
Q	250
S	630

② Series name

Code	Series name
M	Multilayer ceramic capacitor
V	Multilayer ceramic capacitor for high frequency
W	LW reverse type multilayer capacitor

③ End termination

Code	End termination
K	Plated
S	Cu Internal Electrodes

④ Dimension (L × W)

Type	Dimensions (L × W) [mm]	EIA (inch)
042	0.4 × 0.2	01005
063	0.6 × 0.3	0201
105	1.0 × 0.5 0.52 × 1.0	0402 0204
107	1.6 × 0.8 0.8 × 1.6	0603 0306
212	2.0 × 1.25 1.25 × 2.0	0805 0508
316	3.2 × 1.6	1206
325	3.2 × 2.5	1210
432	4.5 × 3.2	1812

Note : ※LW reverse type(□WK) only

⑤ Dimension tolerance

Code	Type	L [mm]	W [mm]	T [mm]
△	ALL	Standard	Standard	Standard
	063	0.6±0.05	0.3±0.05	0.3±0.05
	105	1.0±0.10	0.5±0.10	0.5±0.10
	107	1.6+0.15/-0.05	0.8+0.15/-0.05	0.8+0.15/-0.05
A	212	2.0+0.15/-0.05	1.25+0.15/-0.05	0.45±0.05 0.85±0.10 1.25+0.15/-0.05
	316	3.2±0.20	1.6±0.20	0.85±0.10 1.6±0.20
	325	3.2±0.30	2.5±0.30	2.5±0.30
	063	0.6±0.09	0.3±0.09	0.3±0.09
	105	1.0+0.15/-0.05	0.5+0.15/-0.05	0.5+0.15/-0.05
	107	1.6+0.20/-0	0.8+0.20/-0	0.45±0.05 0.8+0.20/-0
B	212	2.0+0.20/-0	1.25+0.20/-0	0.45±0.05 0.85±0.10 1.25+0.20/-0
	316	3.2±0.30	1.6±0.30	1.6±0.30
C	105	1.0+0.20/-0	0.5+0.20/-0	0.5+0.20/-0

Note: P.6 Standard external dimensions

△= Blank space

⑥ Temperature characteristics code

■ High dielectric type (Excluding Super low distortion multilayer ceramic capacitor (CFCAP™))

Code	Applicable standard		Temperature range [°C]	Ref. Temp. [°C]	Capacitance change	Capacitance tolerance	Tolerance code
BJ	JIS	B	−25~+ 85	20	±10%	±10%	K
	EIA	X5R	−55~+ 85	25		±20%	M
B7	EIA	X7R	−55~+ 125	25	±15%	±10%	K
						±20%	M
C6	EIA	X6S	−55~+ 105	25	±22%	±10%	K
						±20%	M
C7	EIA	X7S	−55~+ 125	25	±22%	±10%	K
						±20%	M
LD(※)	EIA	X5R	−55~+ 85	25	±15%	±10%	K
						±20%	M
△F	JIS	F	−25~+ 85	20	+30/-80%	+80/-20%	Z
	EIA	Y5V	−30~+ 85	25		+22/-82%	Z

Note : ※LD Low distortion high value multilayer ceramic capacitor

△= Blank space

► This catalog contains the typical specification only due to the limitation of space. When you consider the purchase of our products, please check our specification. For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (<http://www.ty-top.com/>).

■ Temperature compensating type

Code	Applicable standard		Temperature range [°C]	Ref. Temp. [°C]	Capacitance change	Capacitance tolerance	Tolerance code		
CG	EIA	C0G	-55~+125	25	0±30ppm/°C	±0.1pF	B		
						±0.25pF	C		
						±0.5pF	D		
						±1pF	F		
						±5%	J		
CH	JIS	CH	-55~+125	20	0±60ppm/°C	±0.1pF	B		
						±0.25pF	C		
						±0.5pF	D		
	EIA	C0H		25		±1pF	F		
						±5%	J		
						±10%	K		
CJ	JIS	CJ	-55~+125	20	0±120ppm/°C	±0.25pF	C		
	EIA	C0J		25					
CK	JIS	CK	-55~+125	20	0±250ppm/°C	±0.25pF	C		
	EIA	C0J		25					
UJ	JIS	UJ	-55~+125	20	-750±120ppm/°C	±0.25pF	C		
	EIA	U2J		25		±0.5pF	D		
						±5%	J		
UK	JIS	UK	-55~+125	20	-750±250ppm/°C	±0.5pF	C		
	EIA	U2K	-55~+125	25					
SL	JIS	SL	-55~+125	20	+350~+1000ppm/°C	±5%	J		

⑥ Series code

(Super low distortion multilayer ceramic capacitor (CFCAP™) only)

Code	Series code
SD	Standard

• Medium-High Voltage Multilayer Ceramic Capacitors

Code	Series code
SD	Standard

⑦ Nominal capacitance

Code (example)	Nominal capacitance
0R5	0.5pF
010	1pF
100	10pF
101	100pF
102	1,000pF
103	10,000pF
104	0.1 μ F
105	1.0 μ F
106	10 μ F
107	100 μ F

Note : R=Decimal point

⑧ Capacitance tolerance

Code	Capacitance tolerance
B	±0.1pF
C	±0.25pF
D	±0.5pF
F	±1pF
G	±2%
J	±5%
K	±10%
M	±20%
Z	+80/-20%

⑨ Thickness

Code	Thickness [mm]
C	0.2
D	
P	0.3
T	
K	0.45
V	
W	0.5
A	0.8
D	0.85(212type or more)
F	1.15
G	1.25
L	1.6
N	1.9
Y	2.0 max
M	2.5

⑩ Special code

Code	Special code
—	Standard

⑪ Packaging

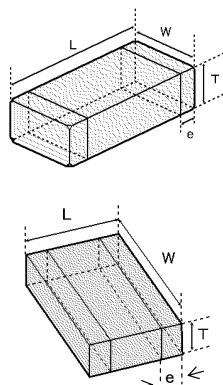
Code	Packaging
F	ϕ 178mm Taping (2mm pitch)
T	ϕ 178mm Taping (4mm pitch)
P	ϕ 178mm Taping (4mm pitch, 1000 pcs/reel) 325 type (Thickness code M)
W	ϕ 178mm Taping(1mm pitch)042type only

⑫ Internal code

Code	Internal code
△	Standard

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■ STANDARD EXTERNAL DIMENSIONS



※ LW reverse type

Type(EIA)	Dimension [mm]				
	L	W	T	*1	e
□MK042(01005)	0.4±0.02	0.2±0.02	0.2±0.02	C D	0.1±0.03
□VS042(01005)	0.4±0.02	0.2±0.02	0.2±0.02		0.1±0.03
□MK063(0201)	0.6±0.03	0.3±0.03	0.3±0.03	P T	0.15±0.05
□MK105(0402)	1.0±0.05	0.5±0.05	0.2±0.02 0.3±0.03 0.5±0.05		0.25±0.10
□VK105(0402)	1.0±0.05	0.5±0.05	0.5±0.05	W	0.25±0.10
□WK105(0204)※	0.52±0.05	1.0±0.05	0.3±0.05	P	0.18±0.08
□MK107(0603)	1.6±0.10	0.8±0.10	0.45±0.05 0.8±0.10	K A	0.35±0.25
□WK107(0306)※	0.8±0.10	1.6±0.10	0.5±0.05	V	0.25±0.15
□MK212(0805)	2.0±0.10	1.25±0.10	0.45±0.05 0.85±0.10 1.25±0.10	K D G	0.5±0.25
□WK212(0508)※	1.25±0.15	2.0±0.15	0.85±0.1	D	0.3±0.2
□MK316(1206)	3.2±0.15	1.6±0.15	0.85±0.10 1.15±0.10 1.25±0.10 1.6±0.20	D F G L	0.5±0.35/-0.25
□MK325(1210)	3.2±0.30	2.5±0.20	0.85±0.10 1.15±0.10 1.9±0.20 1.9±0.1/-0.2 2.5±0.20	N Y M	0.6±0.3
□MK432(1812)	4.5±0.40	3.2±0.30	2.5±0.20	M	0.9±0.6

Note : ※. LW reverse type, *1.Thickness code

■ STANDARD QUANTITY

Type	EIA (inch)	Dimension		Standard quantity [pcs]	
		[mm]	Code	Paper tape	Embossed tape
042	01005	0.2	C	—	40000
			D		
063	0201	0.3	P	15000	—
			T		
105	0402	0.2	C	20000	—
		0.3	P	15000	—
		0.5	V	10000	—
			W		
107	0603	0.30	P	4000	—
		0.45	K		
		0.8	A		
107	0306 ※	0.50	V	—	4000
		0.30	P		
212	0805	0.45	K	4000	—
		0.85	D		
		1.25	G	—	3000
		0.85	D	4000	—
		0.85	D	4000	—
316	1206	1.15	F	—	3000
		1.25	G		
		1.6	L	—	2000
		0.85	D	4000	—
		1.15	F		
325	1210	1.25	G	—	2000
		1.6	L		
		0.85	D		
		1.15	F		
		1.9	N	—	500(T), 1000(P)
		2.0 max	Y		
		2.5	M	—	500
432	1812	2.5	M		

Note : ※.LW Reverse type(□WK)

PARTS NUMBER

[Temperature Characteristic BJ : B/X5R] 1.15mm thickness(F)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
HMK325 BJ104□F-T		100	B X5R ^{*1}	0.1 μ	±10, ±20	3.5	200	1.15±0.10		R	

[Temperature Characteristic B7 : X7R] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
HMK325 B7225□M-T		100		X7R	2.2 μ	±10, ±20	3.5	200	2.5±0.20	R	

[Temperature Characteristic B7 : X7R] 1.9mm thickness(N)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
HMK325 B7154□N-T				X7R	0.15 μ	±10, ±20	3.5	200	1.9±0.20	R	
HMK325 B7224□N-T				X7R	0.22 μ	±10, ±20	3.5	200	1.9±0.20	R	
HMK325 B7334□N-T				X7R	0.33 μ	±10, ±20	3.5	200	1.9±0.20	R	
HMK325 B7474□N-T				X7R	0.47 μ	±10, ±20	3.5	200	1.9±0.20	R	
HMK325 B7684□N-T				X7R	0.68 μ	±10, ±20	3.5	200	1.9±0.20	R	
HMK325 B7105□N-T				X7R	1 μ	±10, ±20	3.5	200	1.9±0.20	R	
QMK325 B7473□N-T				X7R	47000 p	±10, ±20	2.5	150	1.9±0.20	R	
QMK325 B7104□N-T				X7R	0.1 μ	±10, ±20	2.5	150	1.9±0.20	R	
QMK325 B7154□N-T				X7R	0.15 μ	±10, ±20	2.5	150	1.9±0.20	R	
QMK325 B7224□N-T				X7R	0.22 μ	±10, ±20	2.5	150	1.9±0.20	R	
SMK325 B7223□N-T				X7R	22000 p	±10, ±20	2.5	120	1.9±0.20	R	
SMK325 B7333□N-T				X7R	33000 p	±10, ±20	2.5	120	1.9±0.20	R	
SMK325 B7473□N-T				X7R	47000 p	±10, ±20	2.5	120	1.9±0.20	R	

[Temperature Characteristic B7 : X7R] 1.15mm thickness(F)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
HMK325 B7104□F-T		100		X7R	0.1 μ	±10, ±20	3.5	200	1.15±0.10	R	

●432TYPE

[Temperature Characteristic BJ : B/X5R] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
HMK432 BJ474□M-T				B X5R ^{*1}	0.47 μ	±10, ±20	3.5	200	2.5±0.20	R	
HMK432 BJ105□M-T				B X5R ^{*1}	1 μ	±10, ±20	3.5	200	2.5±0.20	R	
HMK432 BJ155□M-T				B X5R ^{*1}	1.5 μ	±10, ±20	3.5	200	2.5±0.20	R	
HMK432 BJ225□M-T				B X5R ^{*1}	2.2 μ	±10, ±20	3.5	200	2.5±0.20	R	
QMK432 BJ104□M-T				B X5R ^{*1}	0.1 μ	±10, ±20	2.5	150	2.5±0.20	R	
QMK432 BJ224□M-T				B X5R ^{*1}	0.22 μ	±10, ±20	2.5	150	2.5±0.20	R	
QMK432 BJ334□M-T				B X5R ^{*1}	0.33 μ	±10, ±20	2.5	150	2.5±0.20	R	
QMK432 BJ474□M-T				B X5R ^{*1}	0.47 μ	±10, ±20	2.5	150	2.5±0.20	R	
SMK432 BJ473□M-T				B X5R ^{*1}	47000 p	±10, ±20	2.5	120	2.5±0.20	R	
SMK432 BJ683□M-T				B X5R ^{*1}	68000 p	±10, ±20	2.5	120	2.5±0.20	R	
SMK432 BJ104□M-T				B X5R ^{*1}	0.1 μ	±10, ±20	2.5	120	2.5±0.20	R	

[Temperature Characteristic B7 : X7R] 2.5mm thickness(M)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
HMK432 B7474□M-T				X7R	0.47 μ	±10, ±20	3.5	200	2.5±0.20	R	
HMK432 B7105□M-T				X7R	1 μ	±10, ±20	3.5	200	2.5±0.20	R	
HMK432 B7155□M-T				X7R	1.5 μ	±10, ±20	3.5	200	2.5±0.20	R	
HMK432 B7225□M-T				X7R	2.2 μ	±10, ±20	3.5	200	2.5±0.20	R	
QMK432 B7104□M-T				X7R	0.1 μ	±10, ±20	2.5	150	2.5±0.20	R	
QMK432 B7224□M-T				X7R	0.22 μ	±10, ±20	2.5	150	2.5±0.20	R	
QMK432 B7334□M-T				X7R	0.33 μ	±10, ±20	2.5	150	2.5±0.20	R	
QMK432 B7474□M-T				X7R	0.47 μ	±10, ±20	2.5	150	2.5±0.20	R	
SMK432 B7473□M-T				X7R	47000 p	±10, ±20	2.5	120	2.5±0.20	R	
SMK432 B7683□M-T				X7R	68000 p	±10, ±20	2.5	120	2.5±0.20	R	
SMK432 B7104□M-T				X7R	0.1 μ	±10, ±20	2.5	120	2.5±0.20	R	

[Temperature Characteristic C6 : X6S, C7 : X7S] 0.3mm thickness(P)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
TKW105 BJ104MP-F		25		X5R	0.1 μ	±20	5	150	0.3±0.05	R	

TKW105 BJ104MP-F		25		X5R	0.1 μ	±20	5	150	0.3±0.05	R	
EWK105 BJ224MP-F		16		X5R	0.22 μ	±20	10	150	0.3±0.05	R	
LWK105 C6224MP-F		10		X5R	0.47 μ	±20	10	150	0.3±0.05	R	
JWK105 C7104MP-F		6.3		X5R ^{*1}	0.1 μ	±20	5	150	0.3±0.05	R	
JWK105 C7474MP-F		6.3		X5R ^{*1}	0.47 μ	±20	10	150	0.3±0.05	R	
JWK105 BJ105MP-F				X5R	1 μ	±20	10	150	0.3±0.05	R	
JWK105 BJ225MP-F				X5R	2.2 μ	±20	10	150	0.3±0.05	R	
AWK105 BJ224MP-F		4		X5R	0.22 μ	±20	10	150	0.3±0.05	R	

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT		Thickness ^{*3} [mm]	Soldering R:Reflow W:Wave
			Rated voltage x %	Thickness ^{*3} [mm]				Rated voltage x %	Thickness ^{*3} [mm]		
EWK105 C6104MP-F		16		X6S	0.1 μ	±20	5	150	0.3±0.05	R	
LWK105 C7104MP-F		10									

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness *3 [mm]	Soldering R:Reflow W:Wave
			X6S	X6S						
AWK105 C6224MP-F		4	X6S	0.22 μ	± 20	10	150	0.3±0.05	R	
AWK105 C6474MP-F			X6S	0.47 μ	± 20	10	150	0.3±0.05	R	
AWK105 C6105MP-F			X6S	1 μ	± 20	10	150	0.3±0.05	R	
AWK105 C6225MP-F			X6S	2.2 μ	± 20	10	150	0.3±0.05	R	

● 107TYPE

【Temperature Characteristic BJ : X5R】0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness *3 [mm]	Soldering R:Reflow W:Wave
			X5R ⁴	X5R ⁴						
TWK107 BJ104MV-T		25	X5R ⁴	0.1 μ	± 20	5	150	0.5±0.05	R	
EWK107 BJ224MV-T			X5R ⁴	0.22 μ	± 20	5	150	0.5±0.05	R	
EWK107 BJ474MV-T			X5R ⁴	0.47 μ	± 20	5	150	0.5±0.05	R	
LWK107 BJ105MV-T			X5R	1 μ	± 20	10	150	0.5±0.05	R	
LWK107 BJ225MV-T		10	X5R	2.2 μ	± 20	10	150	0.5±0.05	R	
JWK107 BJ105MV-T			X5R ⁴	1 μ	± 20	10	150	0.5±0.05	R	
JWK107 BJ225MV-T			X5R	2.2 μ	± 20	10	150	0.5±0.05	R	
JWK107 BJ475MV-T			X5R	4.7 μ	± 20	10	150	0.5±0.05	R	
AWK107 BJ106MV-T		4	X5R	10 μ	± 20	10	150	0.5±0.05	R	

【Temperature Characteristic B7 : X7R, C6 : X6S, C7 : X7S】0.5mm thickness(V)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness *3 [mm]	Soldering R:Reflow W:Wave
			X7R	X7R						
TWK107 B7104MV-T		25	X7R	0.1 μ	± 20	5	150	0.5±0.05	R	
EWK107 B7224MV-T			X7R	0.22 μ	± 20	5	150	0.5±0.05	R	
EWK107 B7474MV-T			X7R	0.47 μ	± 20	5	150	0.5±0.05	R	
JWK107 C7105MV-T			X7S	1 μ	± 20	10	150	0.5±0.05	R	
AWK107 C7225MV-T		6.3	X7S	2.2 μ	± 20	10	150	0.5±0.05	R	
AWK107 C6475MV-T			X6S	4.7 μ	± 20	10	150	0.5±0.05	R	
PKW107 C6106MV-T			X6S	10 μ	± 20	10	150	0.5±0.05	R	

● 212TYPE

【Temperature Characteristic BJ : X5R】0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness *3 [mm]	Soldering R:Reflow W:Wave
			X5R	X5R						
TWK212 BJ475D-T		25	X5R	4.7 μ	$\pm 10, \pm 20$	10	150	0.85±0.10	R	
EWK212 BJ106MD-T			X5R	10 μ	± 20	10	150	0.85±0.10	R	
LWK212 BJ475D-T			X5R	4.7 μ	$\pm 10, \pm 20$	10	150	0.85±0.10	R	
LWK212 BJ106MD-T			X5R	10 μ	± 20	10	150	0.85±0.10	R	
JWK212 BJ226MD-T		6.3	X5R	22 μ	± 20	10	150	0.85±0.10	R	

【Temperature Characteristic B7 : X7R, C6 : X6S】0.85mm thickness(D)

Part number 1	Part number 2	Rated voltage [V]	Temperature characteristics		Capacitance [F]	Capacitance tolerance [%]	tan δ [%]	HTLT	Thickness *3 [mm]	Soldering R:Reflow W:Wave
			X7R	X7R						
TWK212 B7225D-T		25	X7R	2.2 μ	$\pm 10, \pm 20$	5	150	0.85±0.10	R	
EWK212 C6475D-T			X6S	4.7 μ	$\pm 10, \pm 20$	10	150	0.85±0.10	R	
LWK212 C6106MD-T			X6S	10 μ	± 20	10	150	0.85±0.10	R	
AWK212 C6226MD-T			X6S	22 μ	± 20	10	150	0.85±0.10	R	

Multilayer Ceramic Capacitors

■ PACKAGING

① Minimum Quantity

Taped package

Type(EIA)	Thickness		Standard quantity [pcs]	
	mm	code	Paper tape	Embossed tape
□MK042(01005)	0.2	C, D	—	40000
□VS042(01005)	0.2	C	—	—
□MK063(0201)	0.3	P, T	15000	—
□WK105(0204) *	0.3	P	10000	—
□MK105(0402)	0.2	C	20000	—
	0.3	P	15000	—
	0.5	V	10000	—
□VK105(0402) *	0.5	W	4000	—
□MK107(0603)	0.45	K	—	4000
□WK107(0306) *	0.5	V	—	—
□MR107(0603)	0.8	A	—	—
□MK212(0805)	0.45	K	4000	—
□WK212(0508) *	0.85	D	—	—
□MR212(0805)	1.25	G	—	3000
□MK316(1206)	0.85	D	4000	—
□MR316(1206)	1.15	F	—	3000
	1.25	G	—	—
	1.6	L	—	2000
□MK325(1210)	0.85	D	—	—
□MR325(1210)	1.15	F	—	2000
	1.9	N	—	—
	2.0max.	Y	—	—
□MK432(1812)	2.5	M	—	500(T), 1000(P)
	2.5	M	—	500

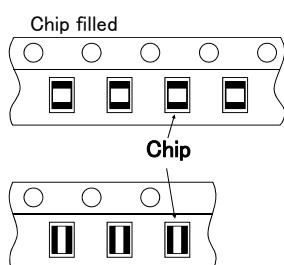
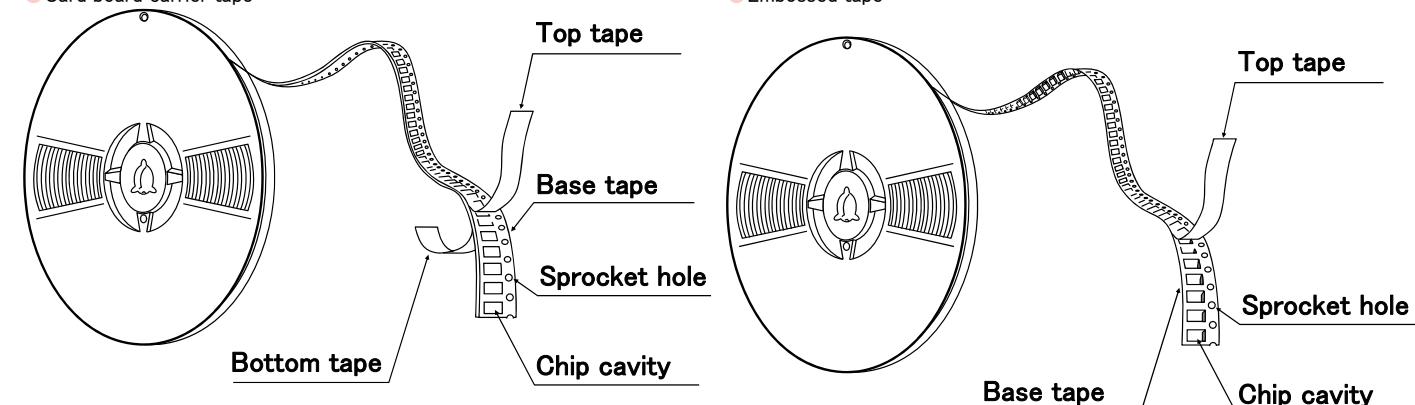
Note : * LW Reverse type.

② Taping material

*No bottom tape for pressed carrier tape

Card board carrier tape

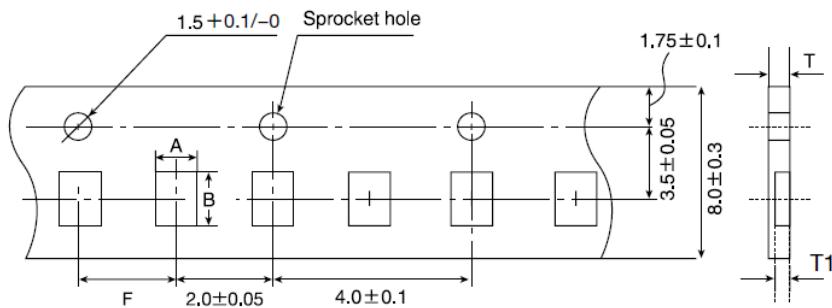
Embossed tape



③ Representative taping dimensions

● Paper Tape (8mm wide)

● Pressed carrier tape (2mm pitch)



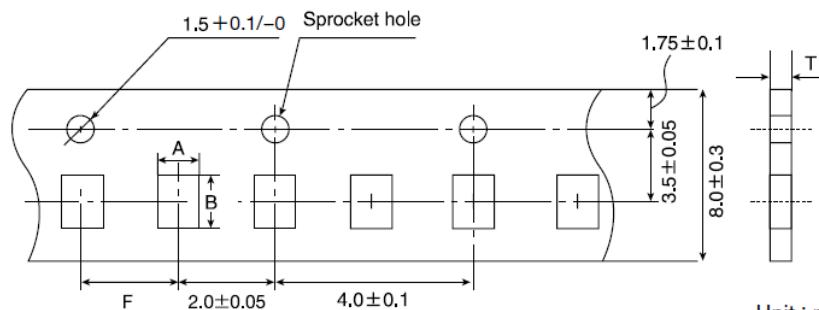
Unit : mm

Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness		
	A	B		T	T1	
□ MK063(0201)	0.37	0.67	2.0 ± 0.05	0.45max.	0.42max.	
□ WK105(0204) ❀	0.65	1.15		0.4max.	0.3max.	
□ MK105(0402) (*1 C)				0.45max.	0.42max.	
□ MK105(0402) (*1 P)						

Note *1 Thickness, C:0.2mm ,P:0.3mm. ❀ LW Reverse type.

Unit:mm

● Punched carrier tape (2mm pitch)

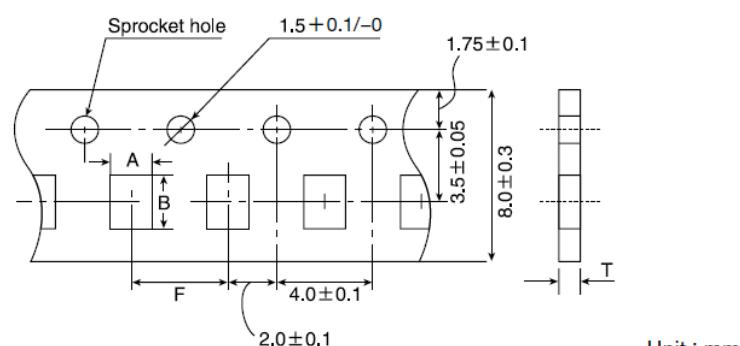


Unit : mm

Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B		
□ MK105 (0402)	0.65	1.15	2.0 ± 0.05	0.8max.
□ VK105 (0402)				

Unit:mm

● Punched carrier tape (4mm pitch)



Unit : mm

Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness
	A	B		
□ MK107(0603)	1.0	1.8	4.0 ± 0.1	1.1max.
□ WK107(0306) ❀				
□ MR107(0603)				
□ MK212(0805)	1.65	2.4		1.1max.
□ WK212(0508) ❀				
□ MK316(1206)	2.0	3.6		

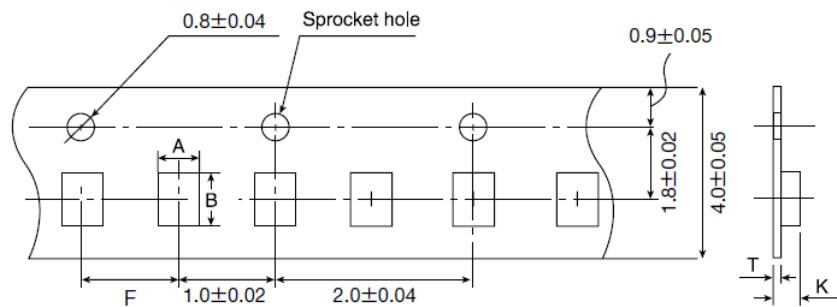
Note:Taping size might be different depending on the size of the product. ❀ LW Reverse type.

Unit:mm

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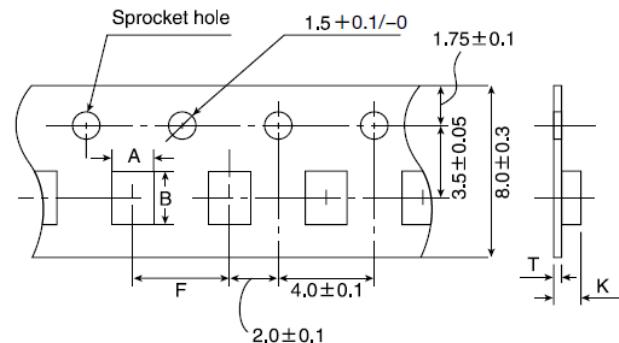
● Embossed tape (4mm wide)



Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B		K	T
□MK042(01005)	0.23	0.43	1.0±0.02	0.5max.	0.25max.
□VS042(01005)					

Unit:mm

● Embossed tape (8mm wide)



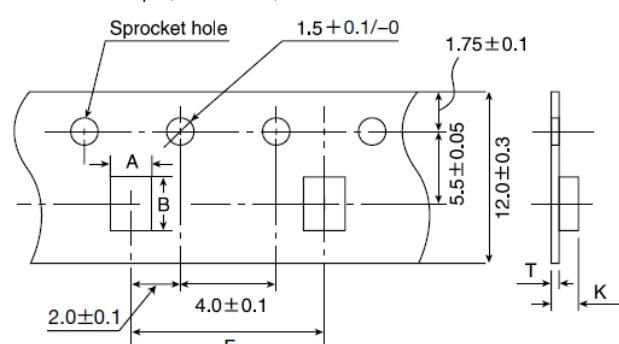
Unit : mm

Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B		K	T
□WK107(0306) ×	1.0	1.8	4.0±0.1	1.3max.	0.25±0.1
□MK212(0805)	1.65	2.4			
□MR212(0805)					
□MK316(1206)	2.0	3.6			
□MR316(1206)					
□MK325(1210)	2.8	3.6			
□MR325(1210)					

Note: × LW Reverse type.

Unit:mm

● Embossed tape (12mm wide)

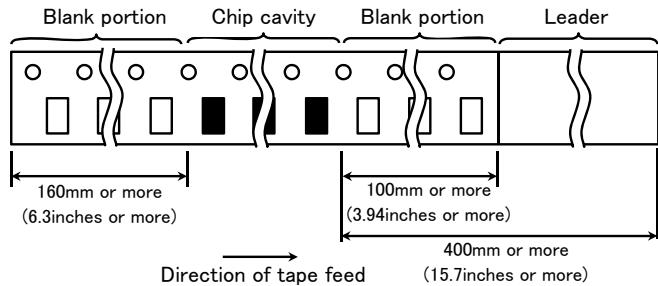


Unit : mm

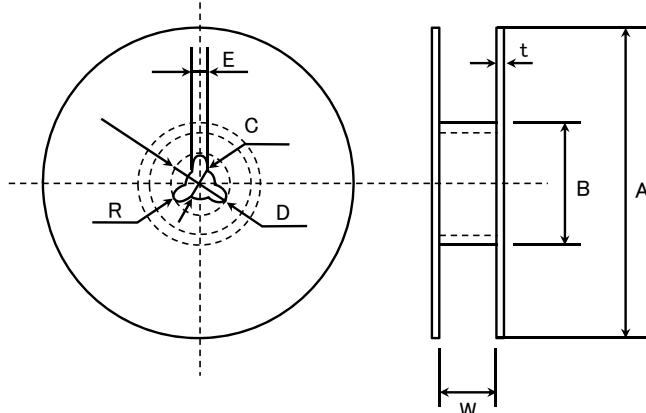
Type(EIA)	Chip Cavity		Insertion Pitch	Tape Thickness	
	A	B		K	T
□MK432(1812)	3.7	4.9	8.0±0.1	4.0max.	0.6max.

Unit:mm

④ Trailer and Leader



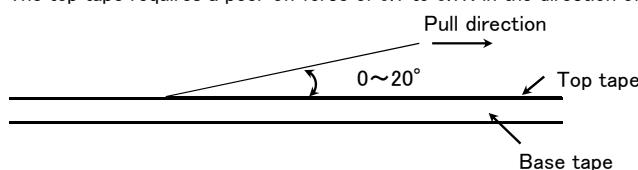
⑤ Reel size



A	B	C	D	E	R
$\phi 178 \pm 2.0$	$\phi 50 \text{min.}$	$\phi 13.0 \pm 0.2$	$\phi 21.0 \pm 0.8$	2.0 ± 0.5	1.0
				Unit:mm	
		T		W	
4mm wide tape		1.5max.		5 ± 1.0	
8mm wide tape		2.5max.		10 ± 1.5	
12mm wide tape		2.5max.		14 ± 1.5	

⑥ Top Tape Strength

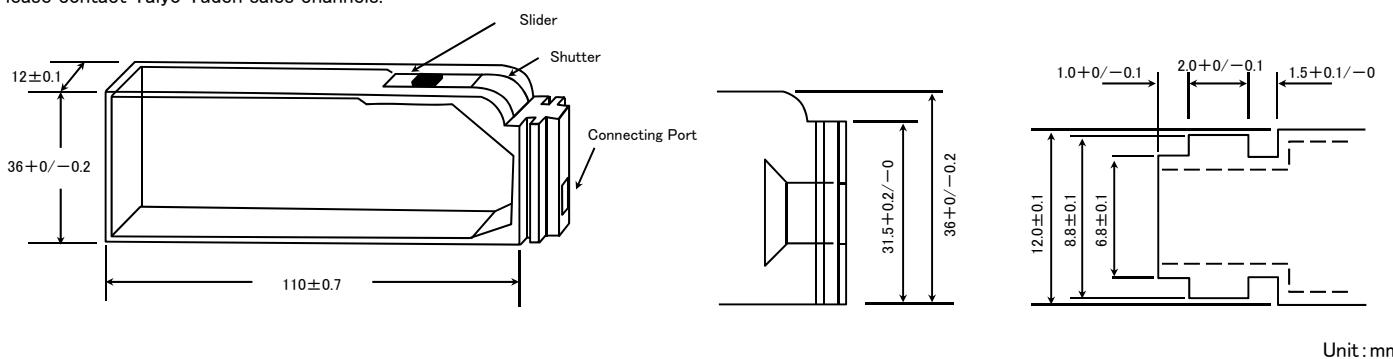
The top tape requires a peel-off force of 0.1 to 0.7N in the direction of the arrow as illustrated below.



⑦ Bulk Cassette

The exchange of individual specification is necessary.

Please contact Taiyo Yuden sales channels.



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Multilayer Ceramic Capacitors

RELIABILITY DATA

1. Operating Temperature Range

Specified Value	Temperature Compensating (Class1)	Standard	-55 to +125°C
		High Frequency Type	
High Permittivity (Class2)		BJ	B -25 to +85°C
		BJ	X5R -55 to +85°C
		B7	X7R -55 to +125°C
		C6	X6S -55 to +105°C
		C7	X7S -55 to +125°C
		LD(※)	X5R -55 to +85°C
		F	F -25 to +85°C
			Y5V -30 to +85°C
		Note: ※LD Low distortion high value multilayer ceramic capacitor	

2. Storage Conditions

Specified Value	Temperature Compensating (Class1)	Standard	-55 to +125°C
		High Frequency Type	
High Permittivity (Class2)		BJ	B -25 to +85°C
		BJ	X5R -55 to +85°C
		B7	X7R -55 to +125°C
		C6	X6S -55 to +105°C
		C7	X7S -55 to +125°C
		LD(※)	X5R -55 to +85°C
		F	F -25 to +85°C
			Y5V -30 to +85°C
		Note: ※LD Low distortion high value multilayer ceramic capacitor	

3. Rated Voltage

Specified Value	Temperature Compensating (Class1)	Standard	50VDC, 25VDC, 16VDC
		High Frequency Type	50VDC, 25VDC, 16VDC
	High Permittivity (Class2)		50VDC, 35VDC, 25VDC, 16VDC, 10VDC, 6.3VDC, 4VDC, 2.5VDC

4. Withstanding Voltage (Between terminals)

Specified Value	Temperature Compensating (Class1)	Standard	No breakdown or damage
		High Frequency Type	
	High Permittivity (Class2)		
Test Methods and Remarks			Class 1
	Applied voltage		Rated voltage × 3
	Duration		1 to 5 sec.
	Charge/discharge current		50mA max.

5. Insulation Resistance

Specified Value	Temperature Compensating (Class1)	Standard	10000 MΩ min.
		High Frequency Type	
	High Permittivity (Class2) Note 1		C≤0.047 μF : 10000 MΩ min. C>0.047 μF : 500MΩ · μF
Test Methods and Remarks	Applied voltage	Rated voltage	
	Duration	: 60±5 sec.	
	Charge/discharge current	: 50mA max.	

6. Capacitance (Tolerance)																	
Specified Value	Temperature Compensating (Class1)	Standard	C□	0.2pF≤C≤5pF	: ±0.25pF												
			U□	0.2pF≤C≤10pF	: ±0.5pF												
	SL		C>10pF		: ±5% or ±10%												
Test Methods and Remarks	High Frequency Type	CH	0.2pF≤C≤2pF	: ±0.1pF													
			C>2pF		: ±5%												
	High Permittivity (Class2)		BJ, B7, C6, C7, LD(※) : ±10% or ±20%, F : +80/-20% Note: ※LD Low distortion high value multilayer ceramic capacitor														
Test Methods and Remarks			Class 1		Class 2												
			Standard	High Frequency Type	C≤10μF												
	Preconditioning		None		Thermal treatment (at 150°C for 1hr) Note 2												
	Measuring frequency		1MHz±10%		1kHz±10%												
	Measuring voltage Note		0.5 to 5Vrms		1±0.2Vrms												
Bias application		None															
7. Q or Dissipation Factor																	
Specified Value	Temperature Compensating (Class1)	Standard	C<30pF : Q≥400+20C C≥30pF : Q≥1000 (C:Nominal capacitance)														
			Refer to detailed specification														
	High Permittivity (Class2)	Note 1	BJ, B7, C6, C7:2.5% max., F:7% max.														
Test Methods and Remarks			Class 1		Class 2												
			Standard	High Frequency Type	C≤10μF												
	Preconditioning		None		Thermal treatment (at 150°C for 1hr) Note 2												
	Measuring frequency		1MHz±10%		1kHz±10%												
	Measuring voltage Note 1		0.5 to 5Vrms		1±0.2Vrms												
Bias application		None															
High Frequency Type																	
Measuring equipment		: HP4291A															
Measuring jig		: HP16192A															
8. Temperature Characteristic (Without voltage application)																	
Specified Value	Temperature Compensating (Class1)	Standard	Temperature Characteristic [ppm/°C]		Tolerance [ppm/°C]												
			C□ : 0	CG,CH, CJ, CK	G : ±30 H : ±60 J : ±120 K : ±250												
			U□ : -750	UJ, UK													
	High Permittivity (Class2)	High Frequency Type	Temperature Characteristic [ppm/°C]		Tolerance [ppm/°C]												
			C□ : 0	CH	H : ±60												
Test Methods and Remarks				Specification	Capacitance change												
			BJ	B	±10%												
				X5R	±15%												
			B7	X7R	±15%												
			C6	X6S	±22%												
			C7	X7S	±22%												
			LD(※)	X5R	±15%												
			F	F	+30/-80%												
				Y5V	+22/-82%												
Note : ※LD Low distortion high value multilayer ceramic capacitor																	
Test Methods and Remarks	Class 1																
	Capacitance at 20°C and 85°C shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.																
	$\frac{(C_{85} - C_{20})}{C_{20} \times \Delta T} \times 10^6 \text{ (ppm/°C)}$			$\Delta T = 65$													
	Class 2																
	Capacitance at each step shall be measured in thermal equilibrium, and the temperature characteristic shall be calculated from the following equation.																
	<table border="1"> <thead> <tr> <th>Step</th> <th>B, F</th> <th>X5R, X7R, X6S, X7S, Y5V</th> </tr> </thead> <tbody> <tr> <td>1</td> <td colspan="2">Minimum operating temperature</td></tr> <tr> <td>2</td> <td>20°C</td> <td>25°C</td></tr> <tr> <td>3</td> <td colspan="2">Maximum operating temperature</td></tr> </tbody> </table>			Step	B, F	X5R, X7R, X6S, X7S, Y5V	1	Minimum operating temperature		2	20°C	25°C	3	Maximum operating temperature			
Step	B, F	X5R, X7R, X6S, X7S, Y5V															
1	Minimum operating temperature																
2	20°C	25°C															
3	Maximum operating temperature																

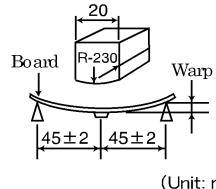
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	$\frac{(C - C_2)}{C_2} \times 100 (\%)$
C	: Capacitance in Step 1 or Step 3
C2	: Capacitance in Step 2

9. Deflection

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 5\%$ or $\pm 0.5 \text{ pF}$, whichever is larger.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 0.5 \text{ pF}$
	High Permittivity (Class2)		Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$ (BJ, B7, C6, C7, LD (※)) Within $\pm 30\%$ (F) Note: ※ LD Low distortion high value multilayer ceramic capacitor

Test Methods and Remarks	<table border="1"> <thead> <tr> <th colspan="3">Multilayer Ceramic Capacitors</th></tr> <tr> <th colspan="2">042, 063, ※105 Type</th><th>The other types</th></tr> </thead> <tbody> <tr> <td>Board</td><td colspan="2">Glass epoxy-resin substrate</td></tr> <tr> <td>Thickness</td><td>0.8mm</td><td>1.6mm</td></tr> <tr> <td>Warp</td><td colspan="2">1mm</td></tr> <tr> <td>Duration</td><td colspan="2">10 sec.</td></tr> </tbody> </table> <p>※105 Type thickness, C: 0.2mm, P: 0.3mm.</p>			Multilayer Ceramic Capacitors			042, 063, ※105 Type		The other types	Board	Glass epoxy-resin substrate		Thickness	0.8mm	1.6mm	Warp	1mm		Duration	10 sec.	
Multilayer Ceramic Capacitors																					
042, 063, ※105 Type		The other types																			
Board	Glass epoxy-resin substrate																				
Thickness	0.8mm	1.6mm																			
Warp	1mm																				
Duration	10 sec.																				



(Unit: mm)

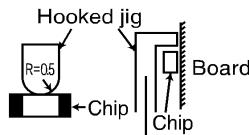
Capacitance measurement shall be conducted with the board bent

10. Body Strength

Specified Value	Temperature Compensating (Class1)	Standard	—
		High Frequency Type	No mechanical damage.
	High Permittivity (Class2)		—
Test Methods and Remarks	High Frequency Type		
	Applied force : 5N		
	Duration : 10 sec.		

11. Adhesive Strength of Terminal Electrodes

Specified Value	Temperature Compensating (Class1)	Standard	No terminal separation or its indication.											
		High Frequency Type												
	High Permittivity (Class2)													
Test Methods and Remarks	<table border="1"> <thead> <tr> <th colspan="3">Multilayer Ceramic Capacitors</th> </tr> <tr> <th colspan="2">042, 063 Type</th> <th>105 Type or more</th> </tr> </thead> <tbody> <tr> <td>Applied force</td> <td>2N</td> <td>5N</td> </tr> <tr> <td>Duration</td> <td colspan="2" rowspan="3">30±5 sec.</td></tr> </tbody> </table>		Multilayer Ceramic Capacitors			042, 063 Type		105 Type or more	Applied force	2N	5N	Duration	30±5 sec.	
Multilayer Ceramic Capacitors														
042, 063 Type		105 Type or more												
Applied force	2N	5N												
Duration	30±5 sec.													



12. Solderability

Specified Value	Temperature Compensating (Class1)	Standard	At least 95% of terminal electrode is covered by new solder.
		High Frequency Type	
	High Permittivity (Class2)		
Test Methods and Remarks	Eutectic solder		At least 95% of terminal electrode is covered by new solder.
	Solder type	H60A or H63A	
	Solder temperature	230±5°C	
	Duration	4±1 sec.	

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13. Resistance to Soldering

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$, whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 7.5\%$ (BJ, B7, C6, C7, LD(※)) Within $\pm 20\%$ (F) Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality Note: ※LD Low distortion high value multilayer ceramic capacitor
Test Methods and Remarks		Class 1	
		042, 063 Type	105 Type
		Preconditioning None	
		Preheating 150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.
		Solder temp. 270±5°C	
		Duration 3±0.5 sec.	
		Recovery 6 to 24 hrs (Standard condition) Note 5	
		Class 2	
		042, 063 Type	105, 107, 212 Type
		Preconditioning Thermal treatment (at 150°C for 1 hr) Note 2	
		Preheating 150°C, 1 to 2 min.	80 to 100°C, 2 to 5 min. 150 to 200°C, 2 to 5 min.
		Solder temp. 270±5°C	
		Duration 3±0.5 sec.	
		Recovery 24±2 hrs (Standard condition) Note 5	

14. Temperature Cycle (Thermal Shock)

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 2.5\%$ or $\pm 0.25\text{pF}$, whichever is larger. Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 0.25\text{pF}$ Q : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 7.5\%$ (BJ, B7, C6, C7, LD(※)) Within $\pm 20\%$ (F) Dissipation factor : Initial value Insulation resistance : Initial value Withstanding voltage (between terminals) : No abnormality Note: ※LD Low distortion high value multilayer ceramic capacitor
Test Methods and Remarks		Class 1	
		Preconditioning None	
		Thermal treatment (at 150°C for 1 hr) Note 2	
		1 cycle	Step Temperature (°C) Time (min.)
			1 Minimum operating temperature 30±3
			2 Normal temperature 2 to 3
			3 Maximum operating temperature 30±3
			4 Normal temperature 2 to 3
	Number of cycles	5 times	
	Recovery	6 to 24 hrs (Standard condition) Note 5 24±2 hrs (Standard condition) Note 5	

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For details of each product (characteristics graph, reliability information, precautions for use, and so on), see our Web site (<http://www.ty-top.com/>).

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15. Humidity (Steady State)

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality		
			Capacitance change : Within $\pm 5\%$ or $\pm 0.5\text{pF}$, whichever is larger.		
			Q : $C < 10\text{pF}$: $Q \geq 200 + 10C$ $10 \leq C < 30\text{pF}$: $Q \geq 275 + 2.5C$ $C \geq 30\text{pF}$: $Q \geq 350$ (C: Nominal capacitance)		
	High Frequency Type		Insulation resistance : $1000 \text{ M}\Omega$ min.		
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 0.5\text{pF}$, Insulation resistance : $1000 \text{ M}\Omega$ min.		
			Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$ (BJ, B7, C6, C7, LD(※)) Within $\pm 30\%$ (F) Dissipation factor : 5.0% max. (BJ, B7, C6, C7, LD(※)) 11.0% max. (F) Insulation resistance : $50 \text{ M}\Omega \mu\text{F}$ or $1000 \text{ M}\Omega$ whichever is smaller. Note: ※LD Low distortion high value multilayer ceramic capacitor		
Test Methods and Remarks		Class 1			
		Standard	High Frequency Type		
	Preconditioning	None			
	Temperature	$40 \pm 2^\circ\text{C}$	$60 \pm 2^\circ\text{C}$		
	Humidity	90 to 95%RH			
	Duration	$500 + 24/-0$ hrs			
	Recovery	6 to 24 hrs (Standard condition) Note 5			
Class 2					
All items					
Thermal treatment (at 150°C for 1 hr) Note 2					
$40 \pm 2^\circ\text{C}$					
90 to 95%RH					
$500 + 24/-0$ hrs					
24 ± 2 hrs (Standard condition) Note 5					

16. Humidity Loading

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality		
			Capacitance change : Within $\pm 7.5\%$ or $\pm 0.75\text{pF}$, whichever is larger.		
			Q : $C < 30\text{pF}$: $Q \geq 100 + 10C/3$ $C \geq 30\text{pF}$: $Q \geq 200$ (C: Nominal capacitance)		
	High Frequency Type		Insulation resistance : $500 \text{ M}\Omega$ min.		
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : $C \leq 2\text{pF}$: Within $\pm 0.4 \text{ pF}$ $C > 2\text{pF}$: Within $\pm 0.75 \text{ pF}$ (C: Nominal capacitance) Insulation resistance : $500 \text{ M}\Omega$ min.		
Test Methods and Remarks		Class 1			
		Standard	High Frequency Type		
	Preconditioning	None			
	Temperature	$40 \pm 2^\circ\text{C}$	$60 \pm 2^\circ\text{C}$		
	Humidity	90 to 95%RH			
	Duration	$500 + 24/-0$ hrs			
	Applied voltage	Rated voltage			
	Charge/discharge current	50mA max.			
	Recovery	6 to 24 hrs (Standard condition) Note 5			
Class 2					
All items					
Voltage treatment (Rated voltage are applied for 1 hour at 40°C) Note 3					
$40 \pm 2^\circ\text{C}$					
90 to 95%RH					
$500 + 24/-0$ hrs					
Rated voltage					
50mA max.					
24 ± 2 hrs (Standard condition) Note 5					

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17. High Temperature Loading

Specified Value	Temperature Compensating (Class1)	Standard	Appearance : No abnormality Capacitance change : Within $\pm 3\%$ or $\pm 0.3\text{pF}$, whichever is larger. Q : $C < 10\text{pF}$: $Q \geq 200 + 10C$ $10 \leq C < 30\text{pF}$: $Q \geq 275 + 2.5C$ $C \geq 30\text{pF}$: $Q \geq 350$ (C : Nominal capacitance) Insulation resistance : $1000 \text{ M}\Omega$ min.
		High Frequency Type	Appearance : No abnormality Capacitance change : Within $\pm 3\%$ or $\pm 0.3\text{pF}$, whichever is larger. Insulation resistance : $1000 \text{ M}\Omega$ min.
	High Permittivity (Class2) Note 1		Appearance : No abnormality Capacitance change : Within $\pm 12.5\%$ (BJ, B7, C6, C7, LD(\times)) Within $\pm 30\%$ (F) Dissipation factor : 5.0% max. (BJ, B7, C6, C7, LD(\times)) 11.0% max. (F) Insulation resistance : $50 \text{ M}\Omega \mu\text{F}$ or $1000 \text{ M}\Omega$, whichever is smaller. Note: \times LD Low distortion high value multilayer ceramic capacitor

	Class 1		Class 2		
	Standard	High Frequency Type	BJ, LD(\times), F	C6	B7, C7
Preconditioning	None		Voltage treatment (Twice the rated voltage shall be applied for 1 hour at 85°C , 105°C or 125°C) Note 3, 4		
Temperature	Maximum operating temperature		Maximum operating temperature		
Duration	$1000 + 48/-0$ hrs		$1000 + 48/-0$ hrs		
Applied voltage	Rated voltage $\times 2$ Note 4		Rated voltage $\times 2$ Note 4		
Charge/discharge current	50mA max.		50mA max.		
Recovery	6 to 24hr (Standard condition) Note 5		24 ± 2 hrs (Standard condition) Note 5		

Note: \times LD Low distortion high value multilayer ceramic capacitor

Note 1 The figures indicate typical specifications. Please refer to individual specifications in detail.

Note 2 Thermal treatment : Initial value shall be measured after test sample is heat-treated at $150 + 0/-10^\circ\text{C}$ for an hour and kept at room temperature for 24 ± 2 hours.

Note 3 Voltage treatment : Initial value shall be measured after test sample is voltage-treated for an hour at both the temperature and voltage specified in the test conditions, and kept at room temperature for 24 ± 2 hours.

Note 4 150% of rated voltage is applicable to some items. Please refer to their specifications for further information.

Note 5 Standard condition: Temperature: 5 to 35°C , Relative humidity: 45 to 85 % RH, Air pressure: 86 to 106kPa When there are questions concerning measurement results, in order to provide correlation data, the test shall be conducted under the following condition.

Temperature: $20 \pm 2^\circ\text{C}$, Relative humidity: 60 to 70 % RH, Air pressure: 86 to 106kPa Unless otherwise specified, all the tests are conducted under the "standard condition".

Precautions on the use of Multilayer Ceramic Capacitors

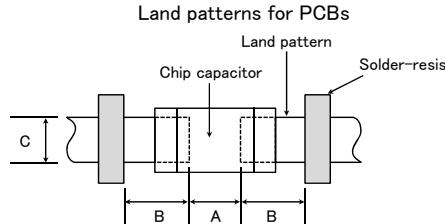
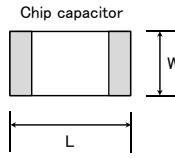
■ PRECAUTIONS

1. Circuit Design

Precautions	◆ Verification of operating environment, electrical rating and performance <ol style="list-style-type: none"> 1. A malfunction of equipment in fields such as medical, aerospace, nuclear control, etc. may cause serious harm to human life or have severe social ramifications. <p>Therefore, any capacitors to be used in such equipment may require higher safety and reliability, and shall be clearly differentiated from them used in general purpose applications.</p>
	◆ Operating Voltage (Verification of Rated voltage) <ol style="list-style-type: none"> 1. The operating voltage for capacitors must always be their rated voltage or less. <p>If an AC voltage is loaded on a DC voltage, the sum of the two peak voltages shall be the rated voltage or less.</p> <p>For a circuit where an AC or a pulse voltage may be used, the sum of their peak voltages shall also be the rated voltage or less.</p> <ol style="list-style-type: none"> 2. Even if an applied voltage is the rated voltage or less reliability of capacitors may be deteriorated in case that either a high frequency AC voltage or a pulse voltage having rapid rise time is used in a circuit.

2. PCB Design

Precautions	◆ Pattern configurations (Design of Land-patterns) <ol style="list-style-type: none"> 1. When capacitors are mounted on PCBs, the amount of solder used (size of fillet) can directly affect the capacitor performance. Therefore, the following items must be carefully considered in the design of land patterns: <ol style="list-style-type: none"> (1) Excessive solder applied can cause mechanical stresses which lead to chip breaking or cracking. Therefore, please consider appropriate land-patterns for proper amount of solder. (2) When more than one component are jointly soldered onto the same land, each component's soldering point shall be separated by solder-resist.
	◆ Pattern configurations (Capacitor layout on PCBs) <p>After capacitors are mounted on boards, they can be subjected to mechanical stresses in subsequent manufacturing processes (PCB cutting, board inspection, mounting of additional parts, assembly into the chassis, wave soldering of the boards, etc.). For this reason, land pattern configurations and positions of capacitors shall be carefully considered to minimize stresses.</p>

Technical considerations	◆ Pattern configurations (Design of Land-patterns) <p>The following diagrams and tables show some examples of recommended land patterns to prevent excessive solder amounts.</p> <p>(1) Recommended land dimensions for typical chip capacitors</p> <p>● Multilayer Ceramic Capacitors : Recommended land dimensions (unit: mm)</p> <p>Wave-soldering</p> <table border="1"> <thead> <tr> <th>Type</th><th>107</th><th>212</th><th>316</th><th>325</th></tr> </thead> <tbody> <tr> <td>Size</td><td>L</td><td>1.6</td><td>2.0</td><td>3.2</td></tr> <tr> <td></td><td>W</td><td>0.8</td><td>1.25</td><td>1.6</td></tr> <tr> <td>A</td><td>0.8 to 1.0</td><td>1.0 to 1.4</td><td>1.8 to 2.5</td><td>1.8 to 2.5</td></tr> <tr> <td>B</td><td>0.5 to 0.8</td><td>0.8 to 1.5</td><td>0.8 to 1.7</td><td>0.8 to 1.7</td></tr> <tr> <td>C</td><td>0.6 to 0.8</td><td>0.9 to 1.2</td><td>1.2 to 1.6</td><td>1.8 to 2.5</td></tr> </tbody> </table>	Type	107	212	316	325	Size	L	1.6	2.0	3.2		W	0.8	1.25	1.6	A	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5	B	0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7	C	0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5
Type	107	212	316	325																											
Size	L	1.6	2.0	3.2																											
	W	0.8	1.25	1.6																											
A	0.8 to 1.0	1.0 to 1.4	1.8 to 2.5	1.8 to 2.5																											
B	0.5 to 0.8	0.8 to 1.5	0.8 to 1.7	0.8 to 1.7																											
C	0.6 to 0.8	0.9 to 1.2	1.2 to 1.6	1.8 to 2.5																											
Land patterns for PCBs 																															
Chip capacitor 																															

Note: Recommended land size might be different according to the allowance of the size of the product.

● LWDC: Recommended land dimensions for reflow-soldering
(unit: mm)

Type	105	107	212	
Size	L	0.52	0.8	1.25
	W	1.0	1.6	2.0
A	0.18 to 0.22	0.25 to 0.3	0.5 to 0.7	
B	0.2 to 0.25	0.3 to 0.4	0.4 to 0.5	
C	0.9 to 1.1	1.5 to 1.7	1.9 to 2.1	



(2) Examples of good and bad solder application

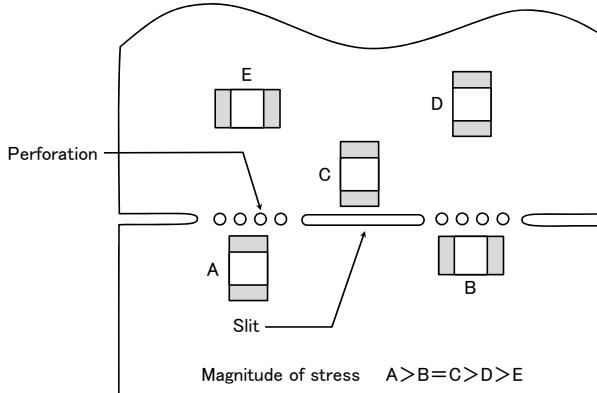
Item	Not recommended	Recommended
Mixed mounting of SMD and leaded components	Lead wire of component	Solder-resist
Component placement close to the chassis	Chassis Solder (for grounding) Electrode pattern	Solder-resist
Hand-soldering of leaded components near mounted components	Lead wire of component Soldering iron	Solder-resist
Horizontal component placement		Solder-resist

◆ Pattern configurations (Capacitor layout on PCBs)

1-1. The following is examples of good and bad capacitor layouts ; capacitors shall be located to minimize any possible mechanical stresses from board warp or deflection.

Items	Not recommended	Recommended
Deflection of board		Place the product at a right angle to the direction of the anticipated mechanical stress.

1-2. The amount of mechanical stresses given will vary depending on capacitor layout. Please refer to diagram below.



1-3. When PCB is split, the amount of mechanical stress on the capacitors can vary according to the method used. The following methods are listed in order from least stressful to most stressful: push-back, slit, V-grooving, and perforation. Thus, please consider the PCB, split methods as well as chip location.

3. Mounting

◆ Adjustment of mounting machine

1. When capacitors are mounted on PCB, excessive impact load shall not be imposed on them.
2. Maintenance and inspection of mounting machines shall be conducted periodically.

◆ Selection of Adhesives

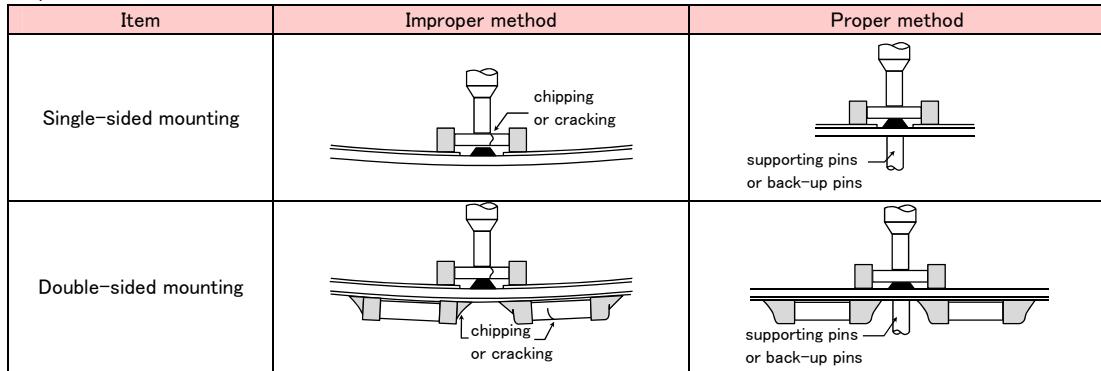
1. When chips are attached on PCBs with adhesives prior to soldering, it may cause capacitor characteristics degradation unless the following factors are appropriately checked : size of land patterns, type of adhesive, amount applied, hardening temperature and hardening period. Therefore, please contact us for further information.

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◆ Adjustment of mounting machine

1. When the bottom dead center of a pick-up nozzle is too low, excessive force is imposed on capacitors and causes damages. To avoid this, the following points shall be considerable.
 - (1) The bottom dead center of the pick-up nozzle shall be adjusted to the surface level of PCB without the board deflection.
 - (2) The pressure of nozzle shall be adjusted between 1 and 3 N static loads.
 - (3) To reduce the amount of deflection of the board caused by impact of the pick-up nozzle, supporting pins or back-up pins shall be used on the other side of the PCB. The following diagrams show some typical examples of good and bad pick-up nozzle placement:



Technical considerations

2. As the alignment pin is worn out, adjustment of the nozzle height can cause chipping or cracking of capacitors because of mechanical impact on the capacitors.
To avoid this, the monitoring of the width between the alignment pins in the stopped position, maintenance, check and replacement of the pin shall be conducted periodically.

◆ Selection of Adhesives

Some adhesives may cause IR deterioration. The different shrinkage percentage of between the adhesive and the capacitors may result in stresses on the capacitors and lead to cracking. Moreover, too little or too much adhesive applied to the board may adversely affect components. Therefore, the following precautions shall be noted in the application of adhesives.

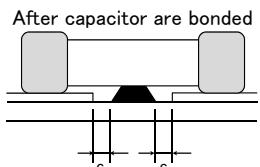
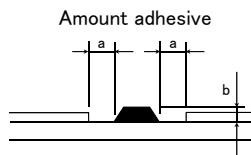
(1) Required adhesive characteristics

- The adhesive shall be strong enough to hold parts on the board during the mounting & solder process.
- The adhesive shall have sufficient strength at high temperatures.
- The adhesive shall have good coating and thickness consistency.
- The adhesive shall be used during its prescribed shelf life.
- The adhesive shall harden rapidly.
- The adhesive shall have corrosion resistance.
- The adhesive shall have excellent insulation characteristics.
- The adhesive shall have no emission of toxic gasses and no effect on the human body.

(2) The recommended amount of adhesives is as follows;

[Recommended condition]

Figure	212/316 case sizes as examples
a	0.3mm min
b	100 to 120 μ m
c	Adhesives shall not contact land



4. Soldering

◆ Selection of Flux

Since flux may have a significant effect on the performance of capacitors, it is necessary to verify the following conditions prior to use;

- (1) Flux used shall be less than or equal to 0.1 wt% (in Cl equivalent) of halogenated content. Flux having a strong acidity content shall not be applied.

- (2) When shall capacitors are soldered on boards, the amount of flux applied shall be controlled at the optimum level.
- (3) When water-soluble flux is used, special care shall be taken to properly clean the boards.

◆ Soldering

Temperature, time, amount of solder, etc. shall be set in accordance with their recommended conditions.

Sn-Zn solder paste can adversely affect MLCC reliability.

Please contact us prior to usage of Sn-Zn solder.

◆ Selection of Flux

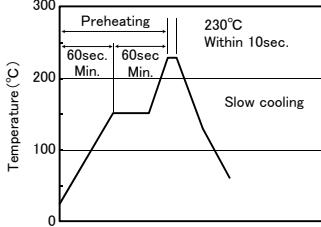
- 1-1. When too much halogenated substance (Chlorine, etc.) content is used to activate flux, or highly acidic flux is used, it may lead to corrosion of terminal electrodes or degradation of insulation resistance on the surfaces of the capacitors.
- 1-2. Flux is used to increase solderability in wave soldering. However if too much flux is applied, a large amount of flux gas may be emitted and may adversely affect the solderability. To minimize the amount of flux applied, it is recommended to use a flux-bubbling system.
- 1-3. Since the residue of water-soluble flux is easily dissolved in moisture in the air, the residues on the surfaces of capacitors in high humidity conditions may cause a degradation of insulation resistance and reliability of the capacitors. Therefore, the cleaning methods and the capability of the machines used shall also be considered carefully when water-soluble flux is used.

◆ Soldering

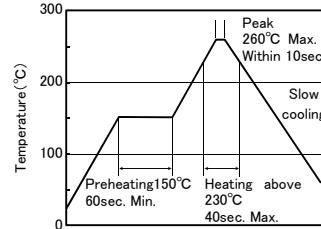
- Ceramic chip capacitors are susceptible to thermal shock when exposed to rapid or concentrated heating or rapid cooling.
- Therefore, the soldering must be conducted with great care so as to prevent malfunction of the components due to excessive thermal shock.
- Preheating : Capacitors shall be preheated sufficiently, and the temperature difference between the capacitors and solder shall be within 130°C.
- Cooling : The temperature difference between the capacitors and cleaning process shall not be greater than 100°C.

[Reflow soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】

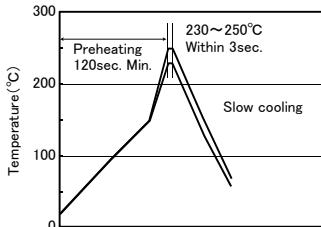


Caution

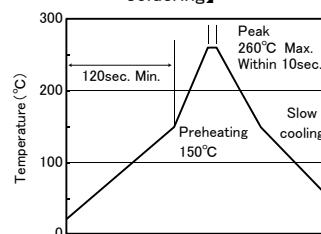
- The ideal condition is to have solder mass (fillet) controlled to 1/2 to 1/3 of the thickness of a capacitor.
- Because excessive dwell times can adversely affect solderability, soldering duration shall be kept as close to recommended times as possible.

[Wave soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】

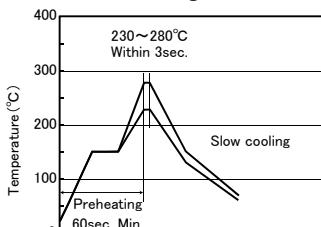


Caution

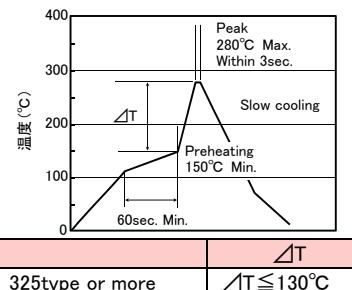
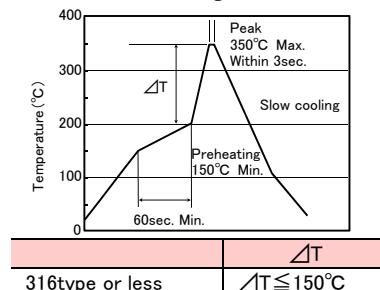
- Wave soldering must not be applied to capacitors designated as for reflow soldering only.

[Hand soldering]

【Recommended conditions for eutectic soldering】



【Recommended condition for Pb-free soldering】



Caution

- Use a 50W soldering iron with a maximum tip diameter of 1.0 mm.
- The soldering iron shall not directly touch capacitors.

5. Cleaning

Precautions	<p>◆ Cleaning conditions</p> <ol style="list-style-type: none"> When PCBs are cleaned after capacitors mounting, please select the appropriate cleaning solution in accordance with the intended use of the cleaning. (e.g. to remove soldering flux or other materials from the production process.) Cleaning condition shall be determined after it is verified by using actual cleaning machine that the cleaning process does not affect capacitor's characteristics.
Technical considerations	<ol style="list-style-type: none"> The use of inappropriate cleaning solutions can cause foreign substances such as flux residue to adhere to capacitors or deteriorate their outer coating, resulting in a degradation of the capacitor's electrical properties (especially insulation resistance). Inappropriate cleaning conditions (insufficient or excessive cleaning) may adversely affect the performance of the capacitors. In the case of ultrasonic cleaning, too much power output can cause excessive vibration of PCBs which may lead to the cracking of capacitors or the soldered portion, or decrease the terminal electrodes' strength. Therefore, the following conditions shall be carefully checked; <ul style="list-style-type: none"> Ultrasonic output : 20 W/l or less Ultrasonic frequency : 40 kHz or less Ultrasonic washing period : 5 min. or less

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6. Resin coating and mold

Precautions	<ol style="list-style-type: none">With some type of resins, decomposition gas or chemical reaction vapor may remain inside the resin during the hardening period or while left under normal storage conditions resulting in the deterioration of the capacitor's performance.When a resin's hardening temperature is higher than capacitor's operating temperature, the stresses generated by the excessive heat may lead to damage or destruction of capacitors. <p>The use of such resins, molding materials etc. is not recommended.</p>
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7. Handling

Precautions	<ul style="list-style-type: none">◆ Splitting of PCB<ol style="list-style-type: none">When PCBs are split after components mounting, care shall be taken so as not to give any stresses of deflection or twisting to the board.Board separation shall not be done manually, but by using the appropriate devices.◆ Mechanical considerations Be careful not to subject capacitors to excessive mechanical shocks.<ol style="list-style-type: none">If ceramic capacitors are dropped onto a floor or a hard surface, they shall not be used.Please be careful that the mounted components do not come in contact with or bump against other boards or components.
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8. Storage conditions

Precautions	<ul style="list-style-type: none">◆ Storage<ol style="list-style-type: none">To maintain the solderability of terminal electrodes and to keep packaging materials in good condition, care must be taken to control temperature and humidity in the storage area. Humidity should especially be kept as low as possible.• Recommended conditions<ul style="list-style-type: none">Ambient temperature : Below 30°CHumidity : Below 70% RH<p>The ambient temperature must be kept below 40°C. Even under ideal storage conditions, solderability of capacitor is deteriorated as time passes, so capacitors shall be used within 6 months from the time of delivery.</p>• Ceramic chip capacitors shall be kept where no chlorine or sulfur exists in the air.2. The capacitance values of high dielectric constant capacitors will gradually decrease with the passage of time, so care shall be taken to design circuits. Even if capacitance value decreases as time passes, it will get back to the initial value by a heat treatment at 150°C for 1hour.
Technical considerations	If capacitors are stored in a high temperature and humidity environment, it might rapidly cause poor solderability due to terminal oxidation and quality loss of taping/packaging materials. For this reason, capacitors shall be used within 6 months from the time of delivery. If exceeding the above period, please check solderability before using the capacitors.

※RCR-2335B (Safety Application Guide for fixed ceramic capacitors for use in electronic equipment) is published by JEITA.

Please check the guide regarding precautions for deflection test, soldering by spot heat, and so on.